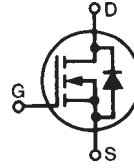


# PolarHT™ HiPerFET Power MOSFET

**IXFH 170N10P**  
**IXFK 170N10P**

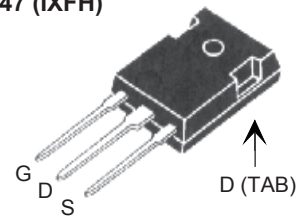
**V<sub>DSS</sub> = 100 V**  
**I<sub>D25</sub> = 170 A**  
**R<sub>DS(on)</sub> ≤ 9.0 mΩ**  
**t<sub>rr</sub> ≤ 150 ns**

N-Channel Enhancement Mode  
Fast Intrinsic Diode  
Avalanche Rated

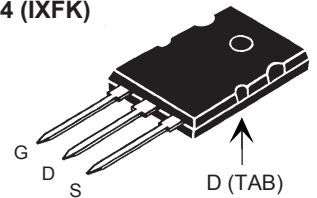


Symbol	Test Conditions	Maximum Ratings	
V <sub>DSS</sub>	T <sub>J</sub> = 25° C to 175° C	100	V
V <sub>DGR</sub>	T <sub>J</sub> = 25° C to 175° C; R <sub>GS</sub> = 1 MΩ	100	V
V <sub>GS</sub>	Continuous	±20	V
V <sub>GSM</sub>	Transient	±30	V
I <sub>D25</sub>	T <sub>C</sub> = 25° C	170	A
I <sub>D(RMS)</sub>	External lead current limit	75	A
I <sub>DM</sub>	T <sub>C</sub> = 25° C, pulse width limited by T <sub>JM</sub>	350	A
I <sub>AR</sub>	T <sub>C</sub> = 25° C	60	A
E <sub>AR</sub>	T <sub>C</sub> = 25° C	80	mJ
E <sub>AS</sub>	T <sub>C</sub> = 25° C	2.0	J
dv/dt	I <sub>S</sub> ≤ I <sub>DM</sub> , di/dt ≤ 100 A/μs, V <sub>DD</sub> ≤ V <sub>DSS</sub> , T <sub>J</sub> ≤ 150° C, R <sub>G</sub> = 4 Ω	10	V/ns
P <sub>D</sub>	T <sub>C</sub> = 25° C	714	W
T <sub>J</sub>		-55 ... +175	°C
T <sub>JM</sub>		175	°C
T <sub>stg</sub>		-55 ... +150	°C
T <sub>L</sub>	1.6 mm (0.062 in.) from case for 10 s	300	°C
T <sub>SOLD</sub>	Plastic body for 10 s	260	°C
M <sub>d</sub>	Mounting torque (TO-3P)	1.13/10	Nm/lb.in.
Weight	TO-3P	5.5	g
	TO-264	10	g
	TO-268	5.0	g

TO-247 (IXFH)



TO-264 (IXFK)



G = Gate      D = Drain  
S = Source    TAB = Drain

### Features

- † International standard packages
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
  - easy to drive and to protect

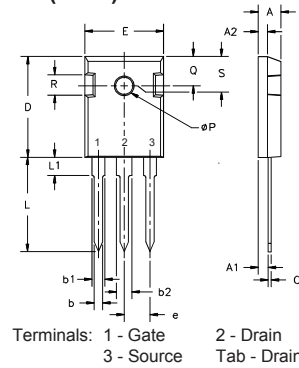
### Advantages

- † Easy to mount
- † Space savings
- † High power density

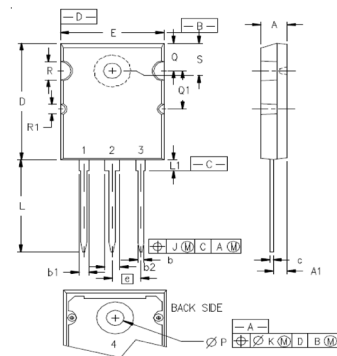
Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	100		V
V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 4 mA	2.5		5.0 V
I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100 nA
I <sub>DSS</sub>	V <sub>DS</sub> = V <sub>DSS</sub> V <sub>GS</sub> = 0 V T <sub>J</sub> = 125° C			25 μA 250 μA
R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 I <sub>D25</sub> V <sub>GS</sub> = 15 V, I <sub>D</sub> = 350A Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %	6.6		9.0 mΩ mΩ

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 10\text{ V}$ ; $I_D = 0.5 I_{D25}$ , pulse test	45	72	S
$C_{iss}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$		6000	pF
$C_{oss}$			2340	pF
$C_{rss}$			730	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}$ , $V_{DS} = 0.5 V_{DSS}$ , $I_D = 60\text{ A}$ $R_G = 3.3\ \Omega$ (External)		35	ns
$t_r$			50	ns
$t_{d(off)}$			90	ns
$t_f$			33	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}$ , $V_{DS} = 0.5 V_{DSS}$ , $I_D = 0.5 I_{D25}$		198	nC
$Q_{gs}$			39	nC
$Q_{gd}$			107	nC
$R_{thJC}$	(TO-264)			$0.21^\circ\text{C/W}$
$R_{thCS}$			0.15	$^\circ\text{C/W}$

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		Min.	Typ.	Max.
$I_s$	$V_{GS} = 0\text{ V}$			170 A
$I_{SM}$	Repetitive			350 A
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			1.5 V
$t_{rr}$	$I_F = 25\text{ A}$ , $-di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 50\text{ V}$ , $V_{GS} = 0\text{ V}$		0.6	150 ns
$Q_{RM}$			8	$\mu\text{C}$
$F_{RM}$				A

**TO-247 (IXFH) Outline**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

**TO-264 (IXFK) Outline**


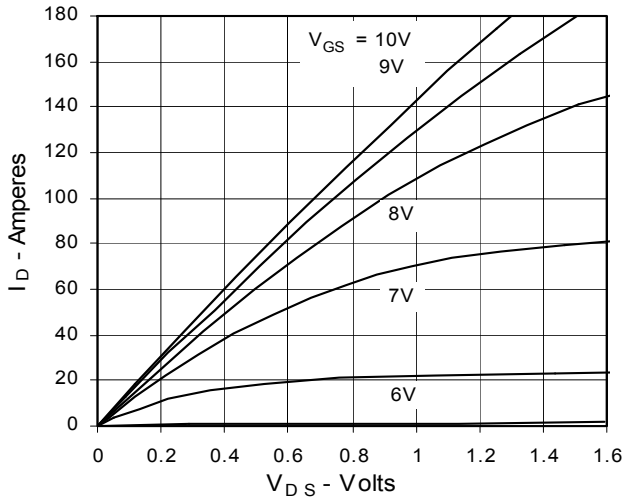
- 1 - GATE  
2, 4 - DRAIN (COLLECTOR)  
3 - SOURCE (EMITTER)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215BSC		5.46 BSC	
J	.000	.010	0.00	0.25
K	.000	.010	0.00	0.25
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
∅P	.122	.138	3.10	3.51
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
∅R	.155	.187	3.94	4.75
∅R1	.085	.093	2.16	2.36
S	.243	.253	6.17	6.43

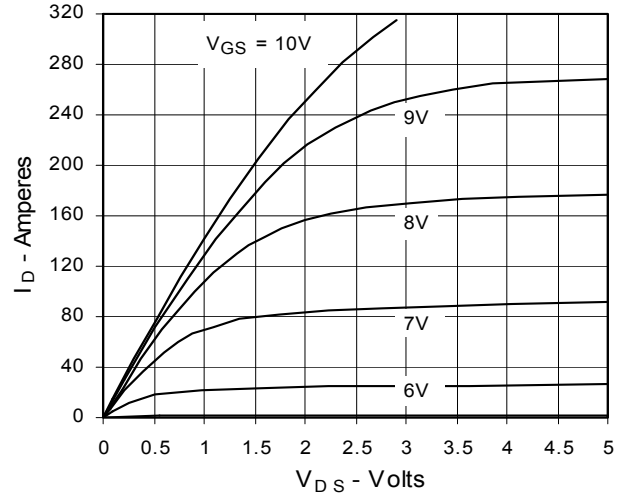
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585  
 one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405B2 6,759,692  
 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

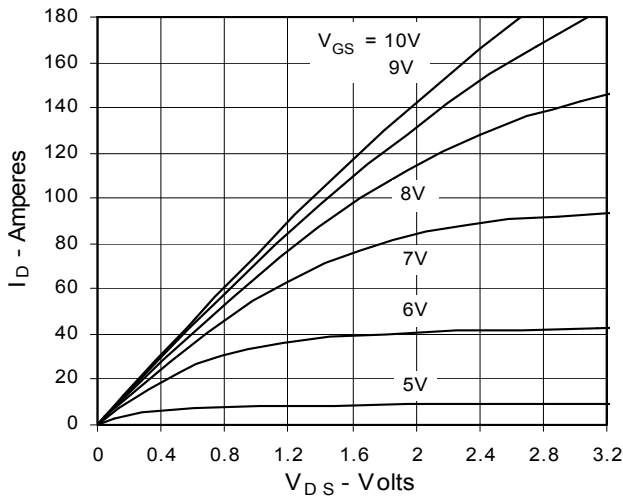
**Fig. 1. Output Characteristics**  
**@ 25°C**



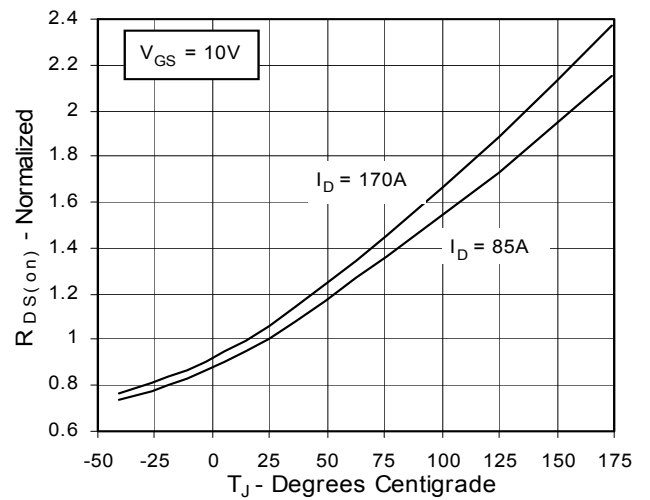
**Fig. 2. Extended Output Characteristics**  
**@ 25°C**



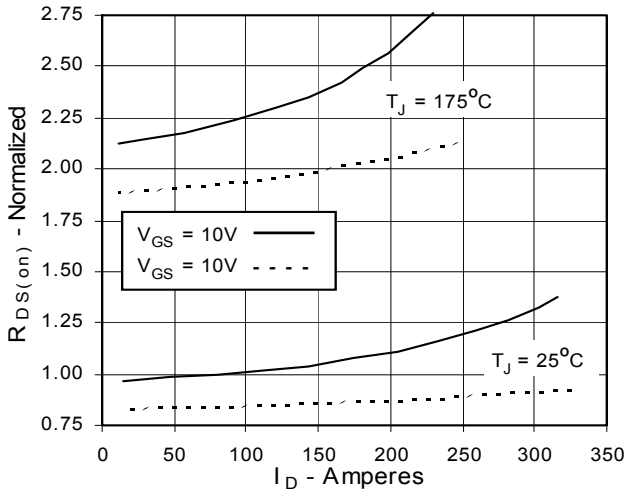
**Fig. 3. Output Characteristics**  
**@ 150°C**



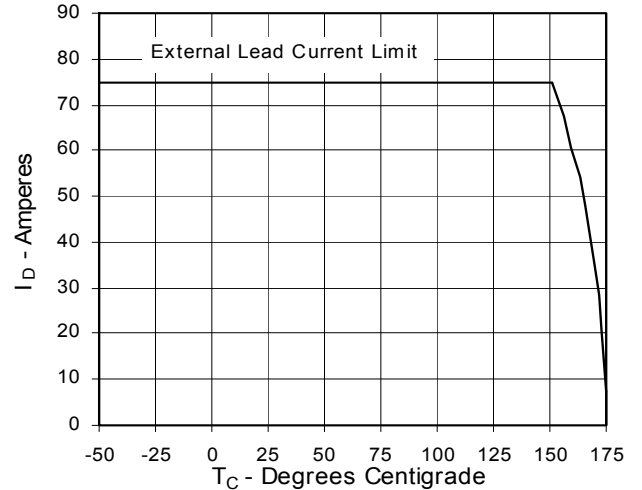
**Fig. 4.  $R_{DS(on)}$  Normalized to 0.5  $I_{D25}$**   
**Value vs. Junction Temperature**



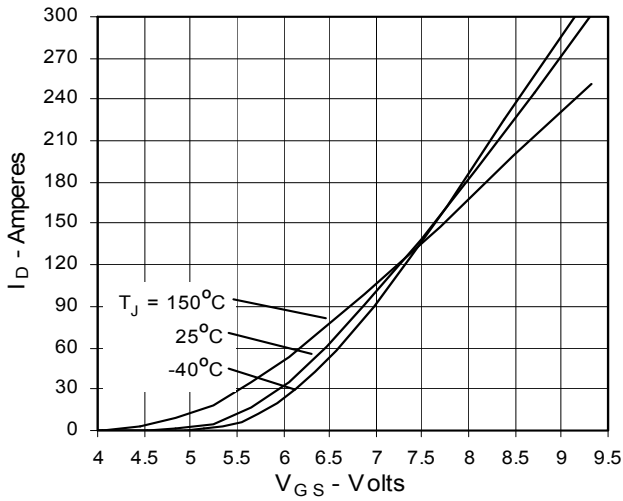
**Fig. 5.  $R_{DS(on)}$  Normalized to 0.5  $I_{D25}$**   
**Value vs. Drain Current**



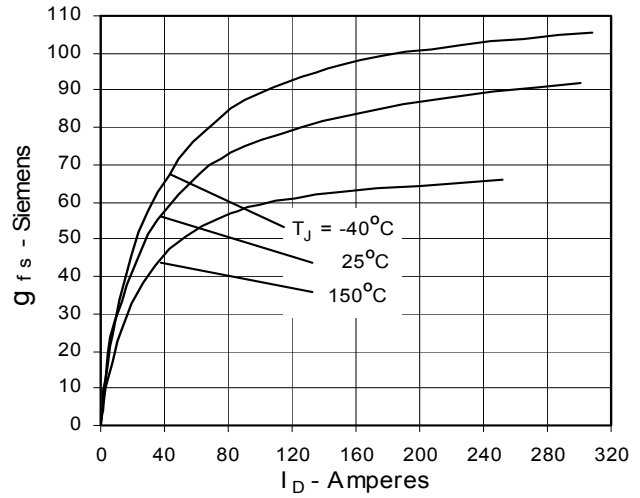
**Fig. 6. Drain Current vs. Case Temperature**



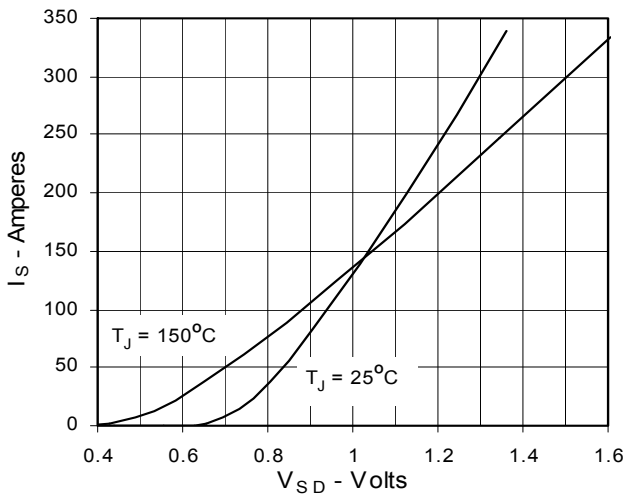
**Fig. 7. Input Admittance**



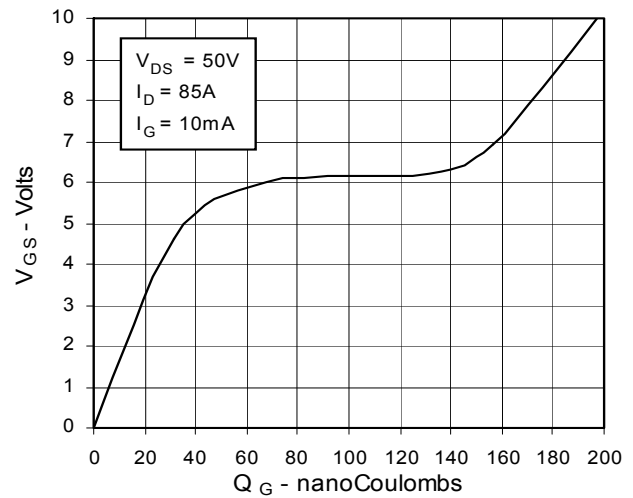
**Fig. 8. Transconductance**



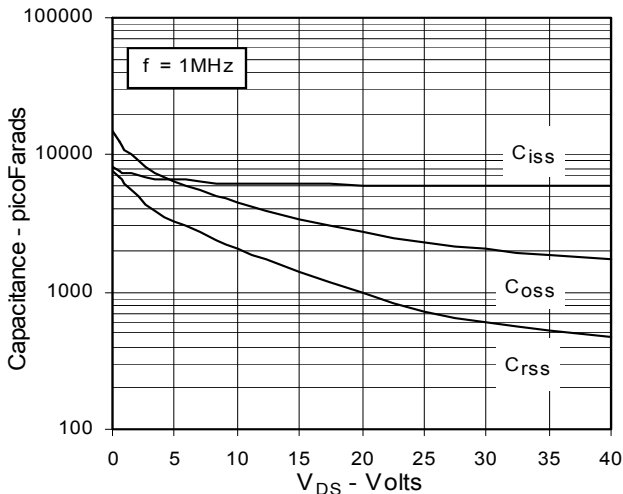
**Fig. 9. Source Current vs. Source-To-Drain Voltage**



**Fig. 10. Gate Charge**



**Fig. 11. Capacitance**



**Fig. 12. Forward-Bias Safe Operating Area**

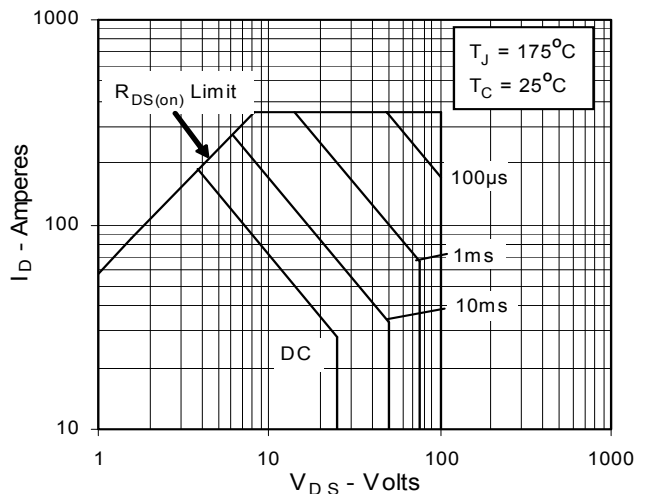


Fig. 13. Maximum Transient Thermal Resistance

